

EL SIDE VIEW LED 57-11-PA0301H-AM



Features

- Package : PLCC 2 package
- Color : Phosphor Converted Amber/Yellow
- Typ. Luminance Intensity : 2800 mcd @ 30mA
- Viewing angle : 120°
- ESD : 8KV
- MSL : 3
- Typ.color coordinates : (0.57,0.41)
- Qualified AEC-Q102
- Sulfur robustness : Class B1
- Compliance with RoHS and REACH
- Compliance with EU REACH.
- Compliance Halogen Free .(Br <900 ppm ,Cl <900 ppm , Br+Cl < 1500 ppm)

Applications

- Automotive Interior Lighting ,
- Switches

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1.Characteristics

Parameter		Symbol	Min.	Typ.	Max.	Unit	Condition
Forward Current		I _F	5	30	60	mA	---
Luminous Intensity		I _v	2240	2800	4500	mcd	I _F =30mA
Forward Voltage		V _F	2.75	3.25	3.75	V	I _F =30mA
Viewing Angle		φ	---	120	---	deg	I _F =30mA
Color		CIE x	---	0.57	---		I _F =30mA
Color		CIE y	---	0.41	---	---	I _F =30mA
Thermal Resistance (Junction to Solder)	Real	R _{th JS real}	---	---	180	K/W	I _F =30mA
	Electrical	R _{th JS el}	---	---	100		

Notes:

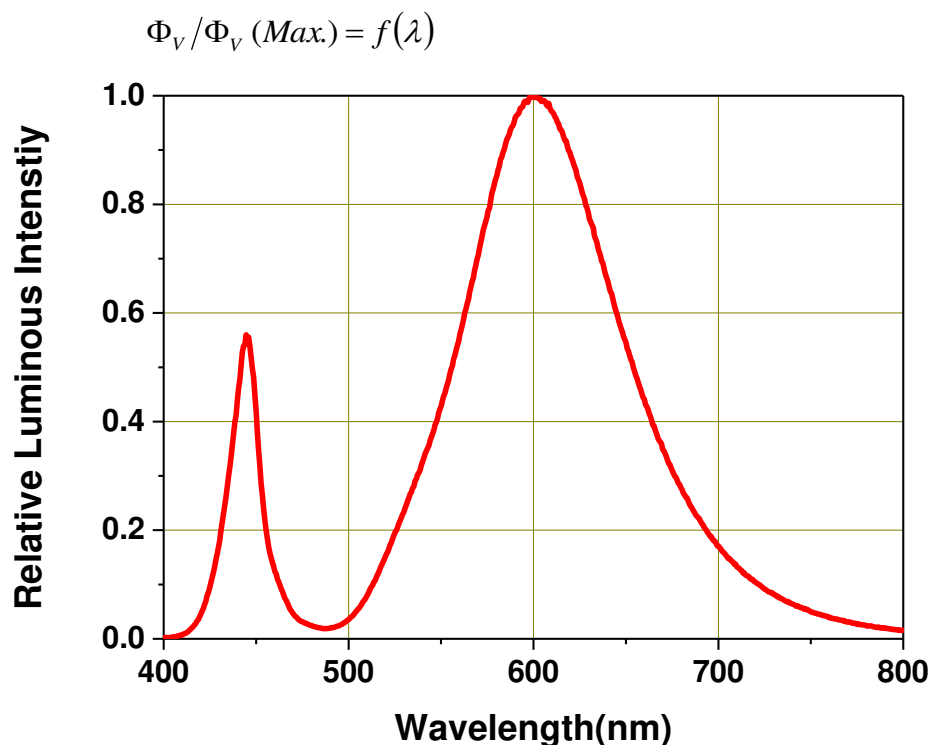
1. Luminous Flux measurement tolerance: ±8%.
2. The data of Luminous Flux measured at thermal pad=25°C
3. Forward voltage measurement tolerance: ±0.05V
4. The V_F range shown in the table above indicates 99% output.
5. Tolerance of Chromaticity Coordinates x,y : ±0.005

2. Absolute Maximum Ratings

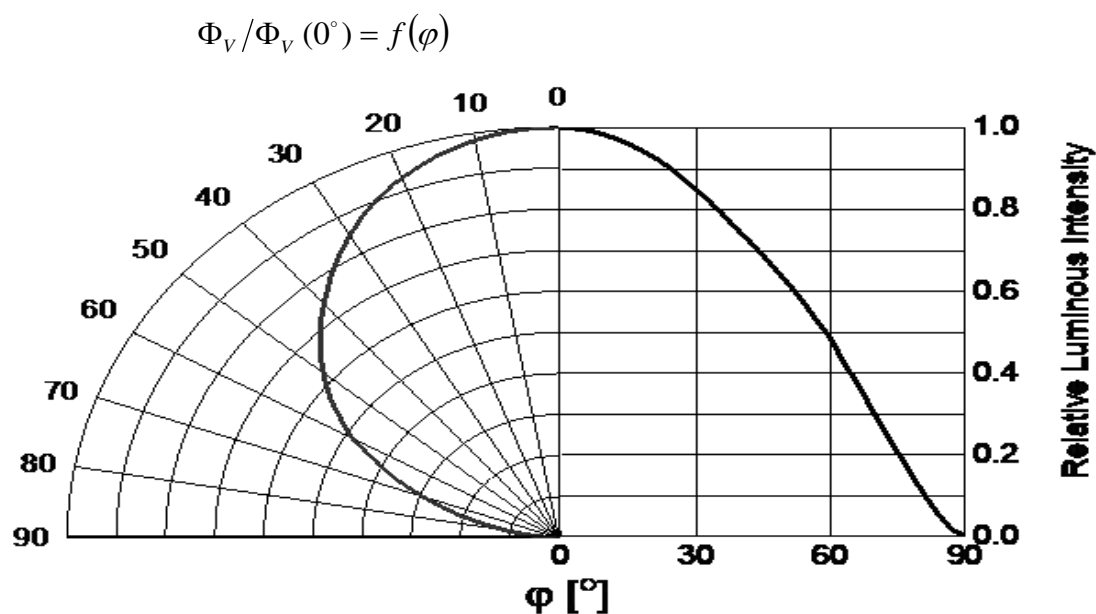
Parameter	Symbol	Ratings	Unit
Power Dissipation	P_d	187	mW
Forward Current	I_F	50	mA
Surge Current ($t \leq 10 \mu s$; $D=0.005$; $T_s=25^\circ C$)	I_{FM}	250	mA
Reverse Voltage	V_R	Not designed for reverse operation	V
Junction Temperature	T_J	125	$^\circ C$
Operating Temperature	T_{opr}	$-40 \sim +110$	$^\circ C$
Storage Temperature	T_{stg}	$-40 \sim +110$	$^\circ C$
ESD Sensitivity ($R=1.5k\Omega$, $C=100pF$)	ESD_{HBM}	8	kV
Soldering Temperature	Reflow	$260^\circ C$ for 30sec	$^\circ C$

3. Characteristics Graph

Wavelength Characteristics Relative Spectral Distribution @ $T_s = 25^\circ\text{C}$, $I_F = 30\text{mA}$



Typical Diagram Characteristics of Radiation

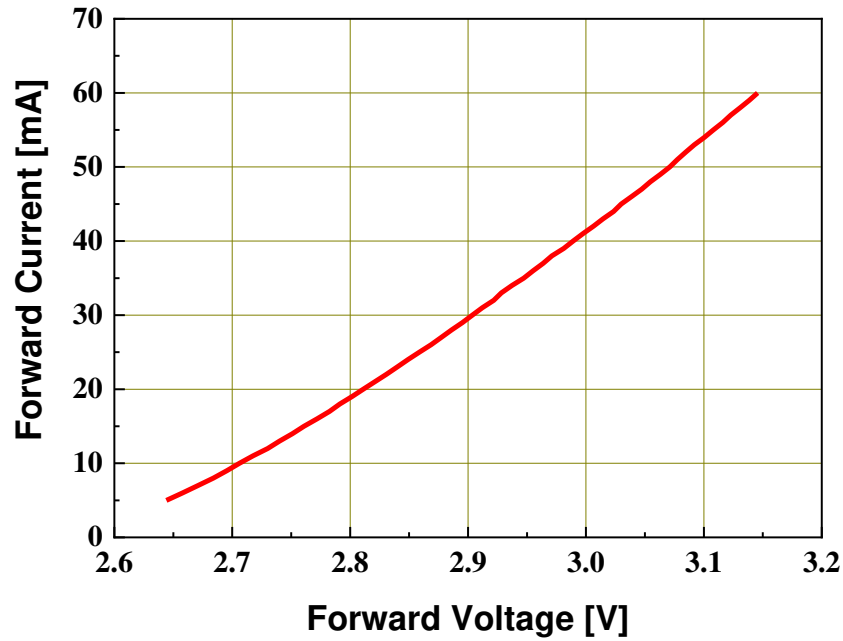


Notes:

1. φ is the off axis angle from lamp centerline where the luminous intensity is 1/2 of the peak value.
2. View angle tolerance is $\pm 5^\circ$.

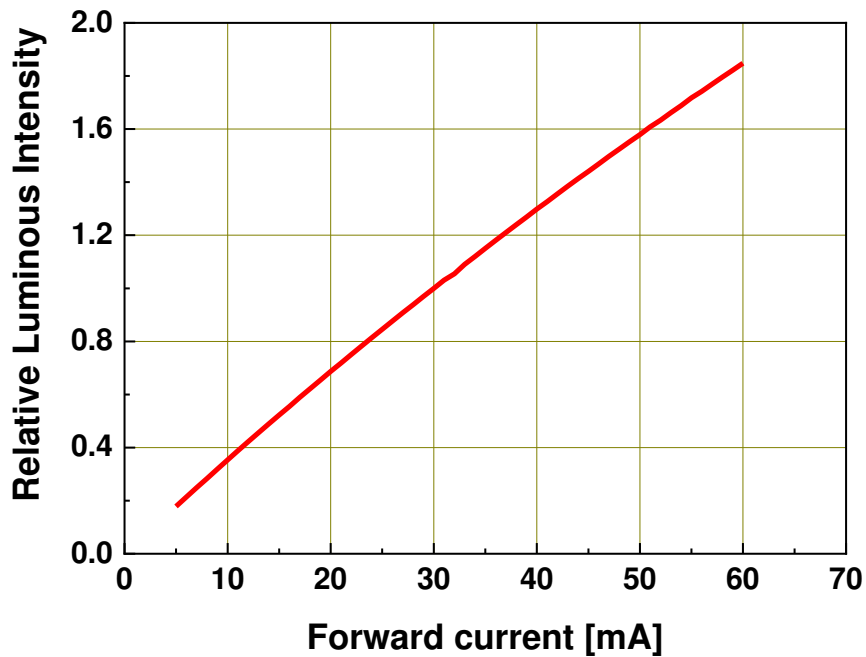
Forward Current vs. Forward Voltage @ Ts = 25°C

$$I_F = f(V_F)$$



Relative Luminous Intensity vs. Forward Current @ Ts = 25°C

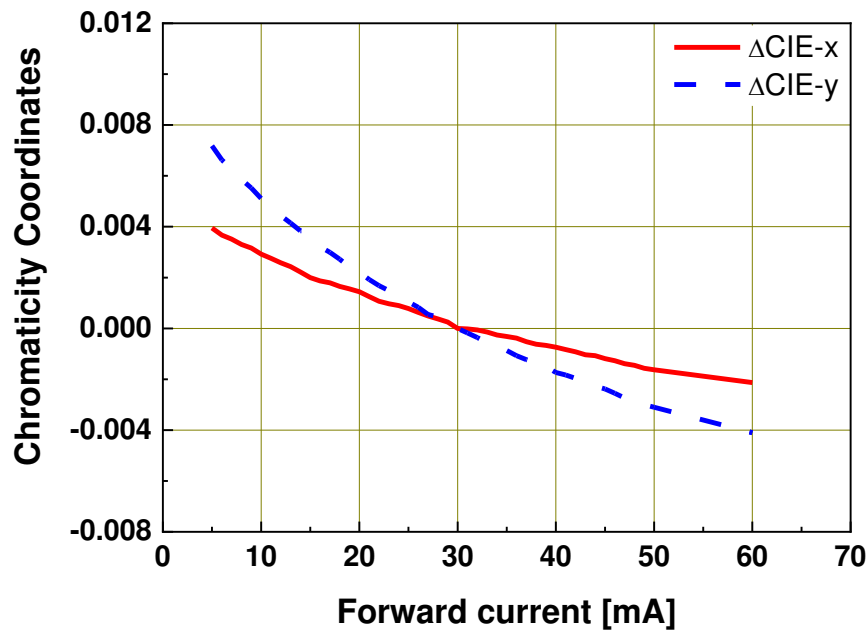
$$\Phi_V / \Phi_V(30mA) = f(I_F)$$



Chromaticity Coordinates Shift vs. Forward Current

@ $T_s = 25^\circ\text{C}$

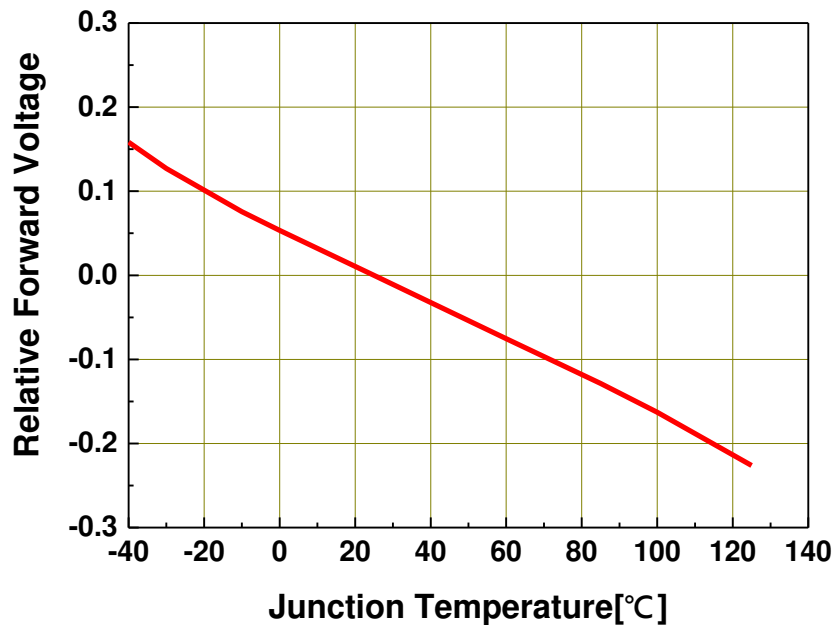
$$\Delta CIE\ x, \Delta CIE\ y = f(I_F)$$



Relative Forward Voltage vs. Junction Temperature

@ $I_F = 30\text{mA}$

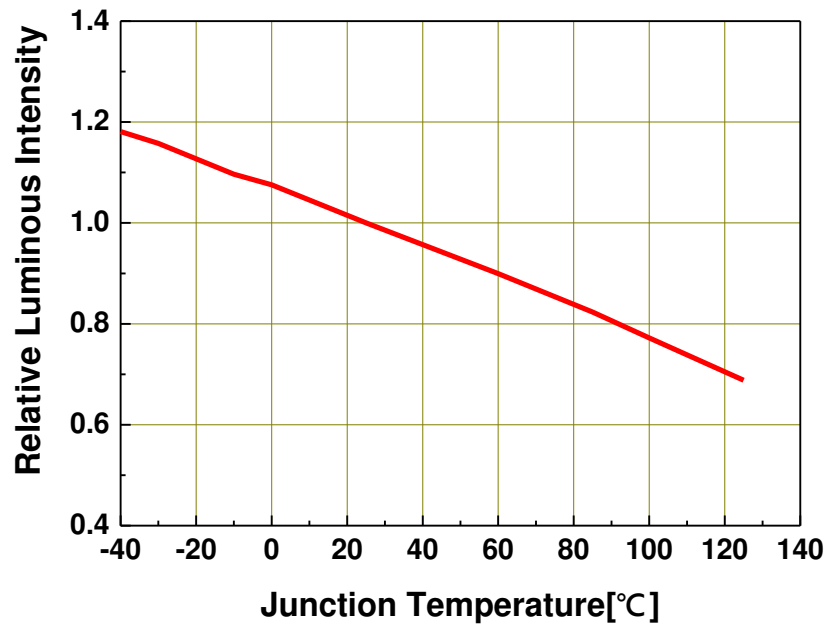
$$\Delta V_F = V_F - V_F(25^\circ\text{C}) = f(T_j)$$



Relative Luminous Intensity vs. Junction Temperature

@ $I_F=30\text{mA}$

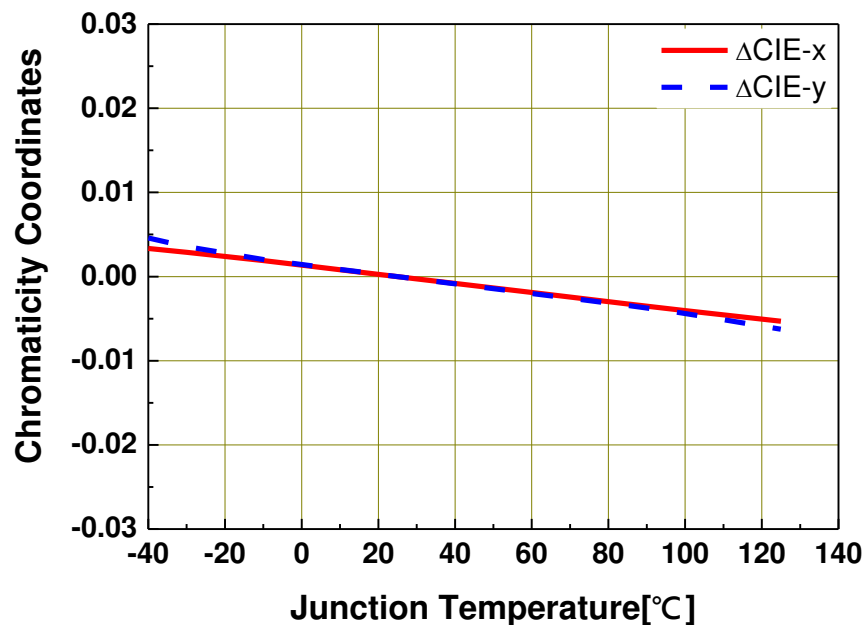
$$\Phi_V / \Phi_V(25^\circ\text{C}) = f(T_j)$$



Chromaticity Coordinates Shift vs. Junction Temperature

@ $I_F=30\text{mA}$

$$\Delta CIE\ x, \Delta CIE\ y = f(T_j)$$





4. Binning Information

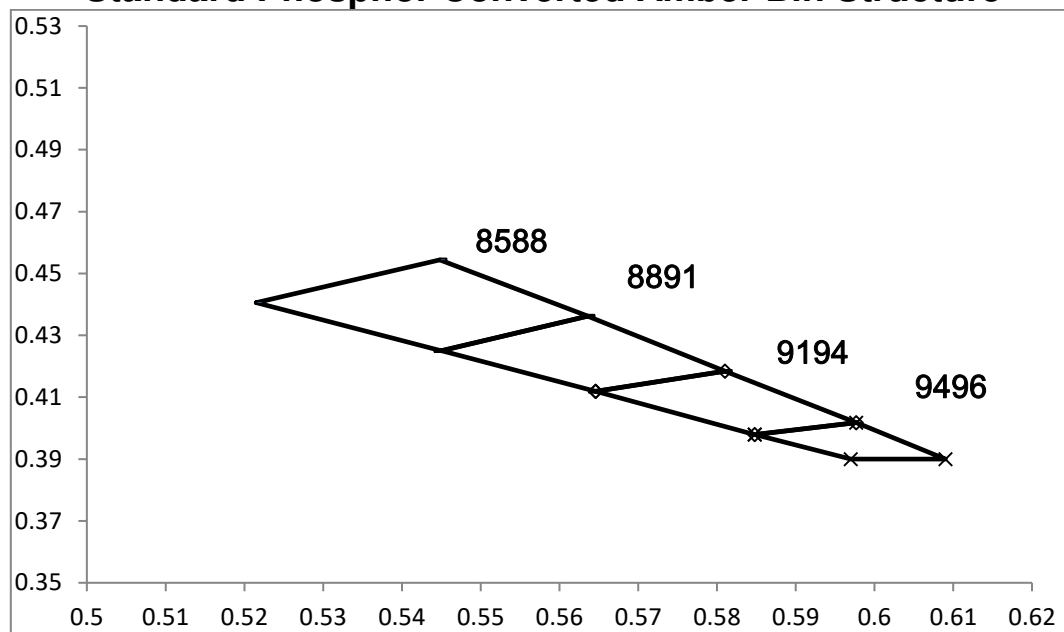
Luminous Intensity Bins

Group Bin	Minimum Luminous Intensity (mcd)	Maximum Luminous Intensity (mcd)
L1	11.2	14
L2	14	18
M1	18	22.4
M2	22.4	28
N1	28	35.5
N2	35.5	45
P1	45	56
P2	56	71
Q1	71	90
Q2	90	112
R1	112	140
R2	140	180
S1	180	224
S2	224	280
T1	280	355
T2	355	450
U1	450	560
U2	560	710
V1	710	900
V2	900	1120
AA	1120	1400
AB	1400	1800
BA	1800	2240
BB	2240	2800
CA	2800	3550
CB	3550	4500
DA	4500	5600
DB	5600	7100
EA	7100	9000
EB	9000	11200
FA	11200	14000
FB	14000	18000
GA	18000	22400

Notes:

- 1. Luminous flux measurement tolerance: ±8%.
- 2. Highlighted Black Box is possible output bins.

Standard Phosphor Converted Amber Bin Structure



Phosphor Converted Amber Bin Coordinates

Bin	CIE x	CIE y
8588	0.5215	0.4406
	0.5448	0.4544
	0.5636	0.4362
	0.5450	0.4250

Bin	CIE x	CIE y
8891	0.5450	0.4250
	0.5636	0.4362
	0.581	0.4184
	0.5646	0.4119

Bin	CIE x	CIE y
9194	0.5646	0.4119
	0.5810	0.4184
	0.5977	0.4018
	0.5848	0.3979

Bin	CIE x	CIE y
9496	0.5848	0.3979
	0.5977	0.4018
	0.6090	0.3900
	0.5970	0.3900

Notes:

1. Color coordinates measurement allowance: ± 0.005

Forward Voltage Bins

Bin code	Min Forward Voltage [V]	Max Forward Voltage [V]
1012	1.00	1.25
1215	1.25	1.50
1517	1.50	1.75
1720	1.75	2.00
2022	2.00	2.25
2225	2.25	2.50
2527	2.50	2.75
2730	2.75	3.00
3032	3.00	3.25
3235	3.25	3.50
3537	3.50	3.75
3740	3.75	4.00
4042	4.00	4.25
4245	4.25	4.50
4547	4.50	4.75
4750	4.75	5.00
5052	5.00	5.25
5255	5.25	5.50
5557	5.50	5.75
5760	5.75	6.00
6062	6.00	6.25
6265	6.25	6.50
6567	6.50	6.75
6770	6.75	7.00

Notes:

- Forward voltage measurement tolerance: $\pm 0.05\text{V}$.
- Forward voltage bins are defined at $I_F = 30\text{mA}$ operation.

5. Part Number

57-11-PA0301H-AM

Part number is designated with below details.

57-11 = Product family name.

PA = Color ^[1]

030 = Test current [mA]

0 = internal code

H = Brightness Level (H=High ; M=Medium ; L=Low)

AM = Automotive application

Note

[1] Color :

Symbol	Description
C	Cool White
N	Neutral White
W	Warm White
PA	Phosphor Converted Amber
PR	Phosphor Converted Red
UB	Blue
IB	Ice Blue
SB	Sky Blue
UP	Purple
UG	Green
UY	Yellow
UYG	Brilliant Yellow Green
UPG	Pale Green
UA	Amber
UR	Red
SR	Super Red
RGB	RGB-Color
PYG	Phosphor Converted Yellow Green

6. Ordering Information

57-11-PA0301H-**ABCDEFGHJKLM-NO-AM**

Part Number of the 57-11	Order Code
57-11-PA0301H-AM	57-11-PA0301H-ABCDEFGHJKLM-NO-AM

Order code contains information with below details :

ABCD = min/max wavelength or CCT

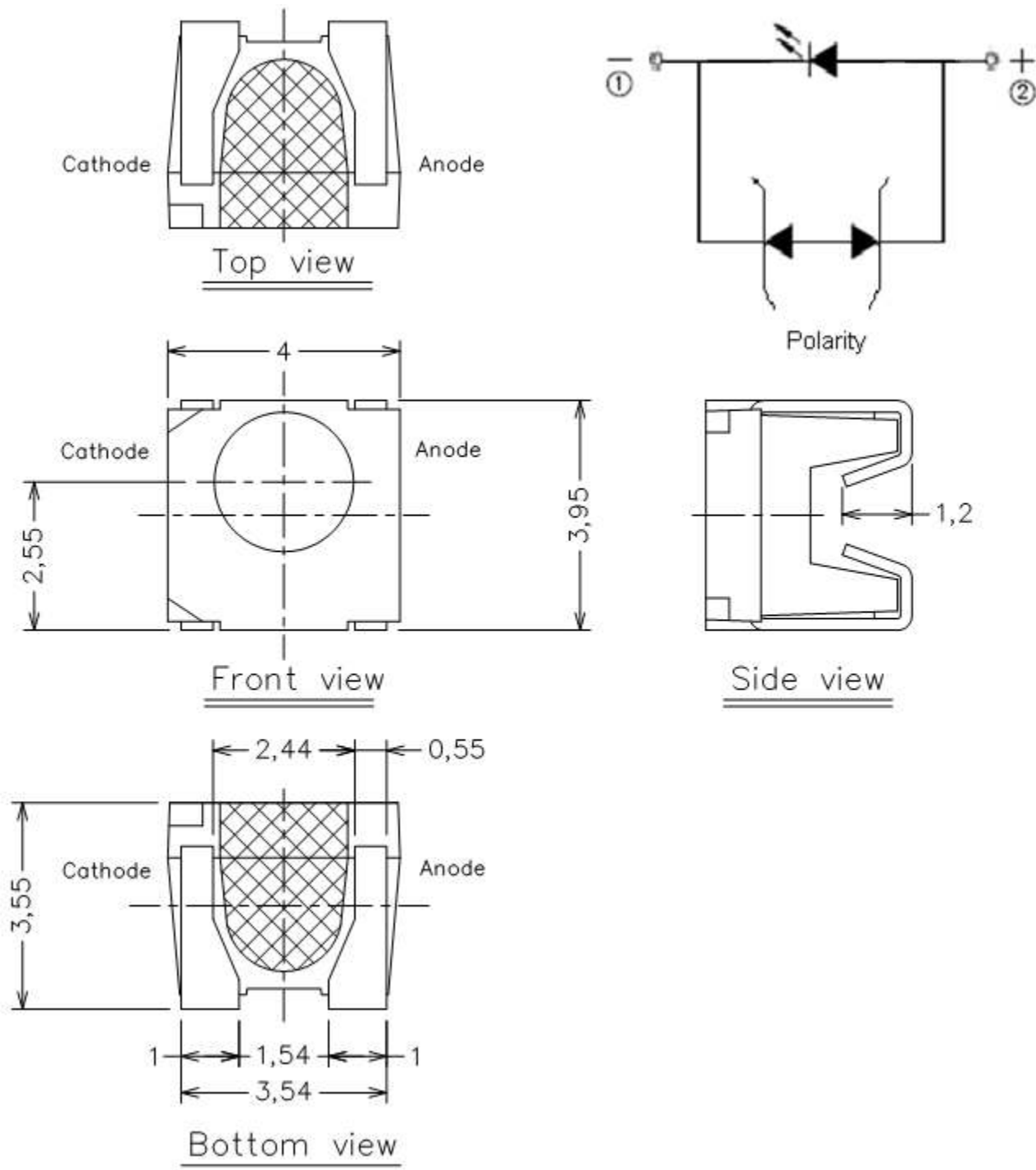
EFGH = min./max. luminous flux in [lm] or luminous intensity in [mcd]

JKLM = min./max. forward voltage

NO = internal code

AM = Automotive Application

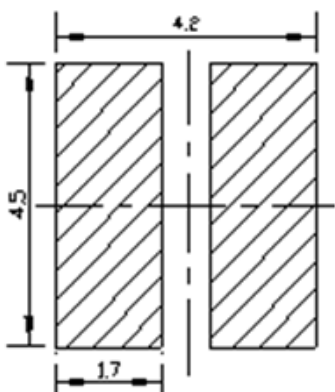
7. Mechanical Dimension



Notes:

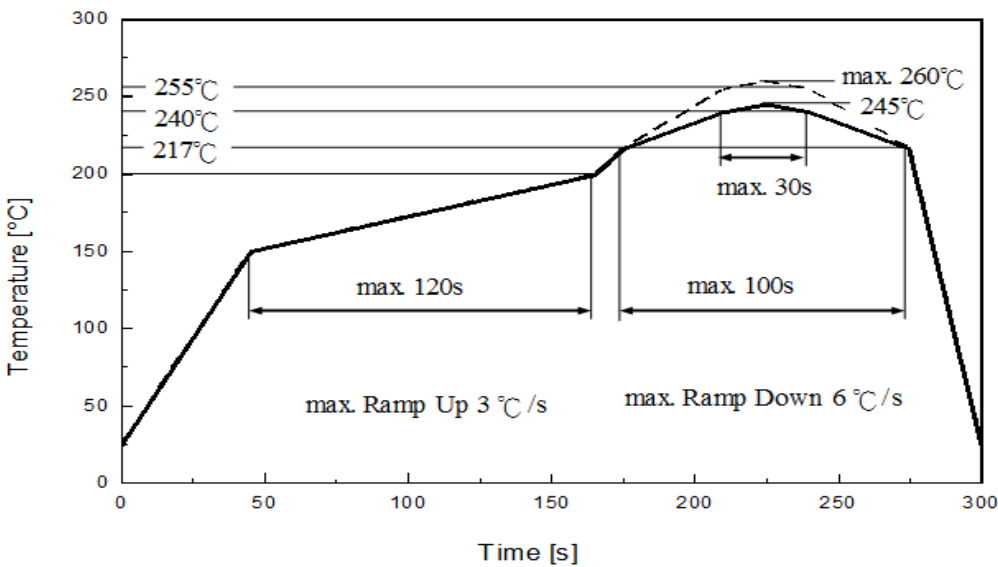
1. Dimensions are in millimeters.
2. Tolerances unless mentioned are $\pm 0.1\text{mm}$.

8. Recommended Soldering Pad



9. Reflow Soldering Profile

Soldering Condition (Reference: IPC/JEDEC J-STD-020D)



Profile Feature	Pb-Free Assembly	Unit
	Recommendation	
Ramp-up rate to preheat 25 °C to 150 °C	3	°C /sec
Time of soaking zone 150 °C to 200 °C	120	sec
Ramp-up rate to peak	3	°C /sec
Liquidus temperature	217	°C
Time above liquidus temperature	100	sec
Peak temperature (max.)	260	°C
Time within 5°C of the specified peak temperature	30	sec
Ramp-down Rate (max.)	6	°C /sec

10. Packaging Information

• Product Labeling

RoHS

Pb

EVERLIGHT

5

CPN : XXXXXXXXXXXXXXXXXXXX

XXXXXXXXXX-XXXXXXXXXX-XXXXXXXXXX-XXXXXXXXXX-XXXXXX

P/N : XXXXXXXXXXXX

XXXXXXXXXX-XXXXXXXXXX-XXXXXXXXXX-XXXXXXXXXX-XXXXXX

LOT No:Y150716XXX-XXXXXXXXXX-XXXXXXXXXX

QTY: 0123456789 HUE: XXXXXXXXXXXX

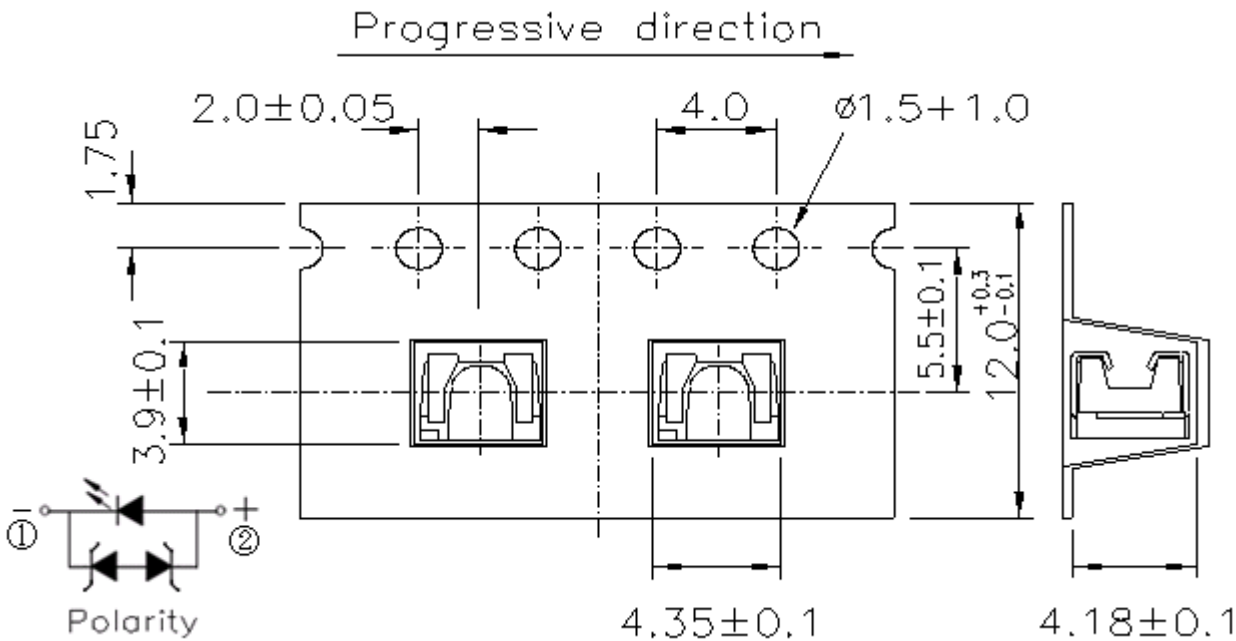
CAT: XXXXXXXXXXXX REF: XXXXXXXXXXXX

REFERENCE: BTPYYMDDXXXXX

MSL-X MADE IN XXXXXX

- CPN : Customer's Product Number
- P/N : Everlight Part Number
- QTY : Packing Quantity
- CAT : Luminous Flux (Brightness) Bin
- HUE : Color Bin
- REF : Forward Voltage Bin
- LOT No : Lot Number

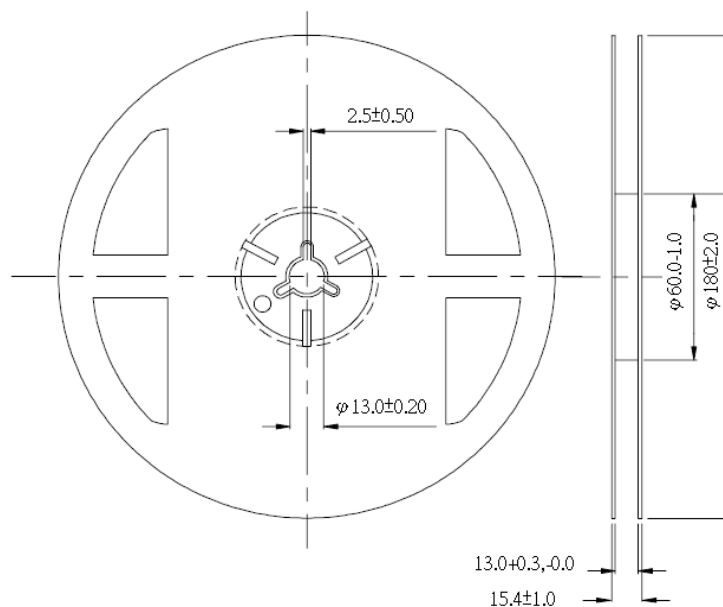
• Packing: Loaded Quantity 500 pcs Per Reel



Notes:

- 1. Dimensions are in millimeters.
- 2. Tolerances for fixed dimensions are ±0.2mm.

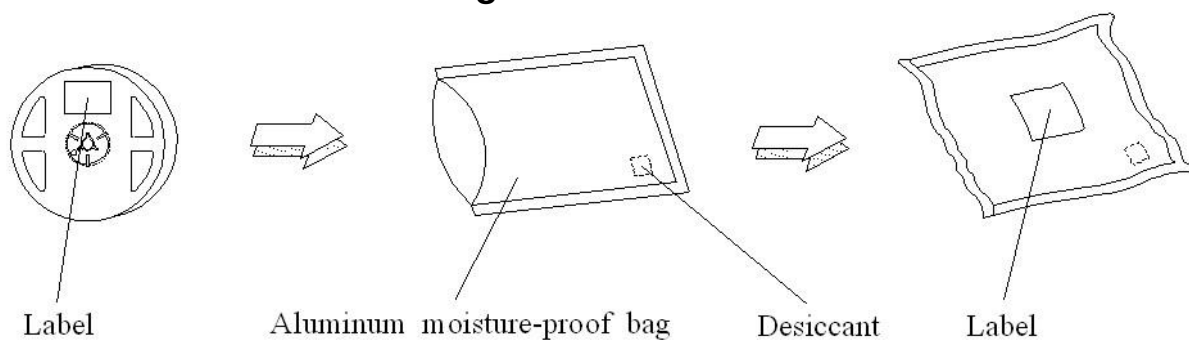
• Reel Dimensions



Notes:

1. Dimensions are in millimeters.
2. Tolerances for fixed dimensions are $\pm 0.2\text{mm}$.

• Moisture Resistant Packing Process



11. Precaution for Use

1. Over-current-proof

Customer must apply resistors for protection; otherwise slight voltage shift will cause big current change (burn out will happen).

2. Assemblies

Do not stack assemblies containing LEDs to prevent damage to the optical surface of LEDs. Forces applied to the optical surface may result in the surface being damaged.

3. Soldering Condition

3.1 When soldering, do not put stress on the LEDs during heating.

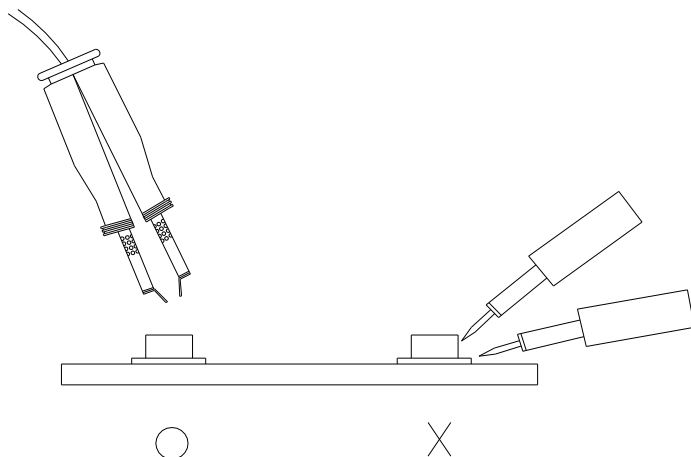
3.2 After soldering, do not warp the circuit board.

4. Soldering Iron

Each terminal is to go to the tip of soldering iron temperature less than 350°C for 3 seconds within once in less than the soldering iron capacity 25W. Leave two seconds and more intervals, and do soldering of each terminal. Be careful because the damage of the product is often started at the time of the hand solder.

5. Repairing

Repair should not be done after the LEDs have been soldered. When repairing is unavoidable, a double-head soldering iron should be used (as below figure). It should be confirmed beforehand whether the characteristics of the LEDs will or will not be damaged by repairing.



12. Sulfur Test Criteria

Products		Failure Criteria		
Exterior Lighting products		Luminous Flux +/-20%, forward voltage +/-10%, color coordinates x,y +/-0.01, color wavelength +/- 2 nm Visual defect issue following Everlight's inspection criteria		
Interior lighting products		Luminous Flux +/-30% or +/-50% for some application, forward voltage +/-10%, color coordinates x,y +/-0.02, color wavelength +/- 2 nm Visual defect issue following Everlight's inspection criteria		
Grade of H2S and FMG test		Please refer to the table as below. As for discolor, please refer to the Frame blackening after Grade of H2S and FMG test defect under Everlight's inspection criteria		
	Grade A0	Grade A1	Grade B0	Grade B1
C12 H2S Class A C13 FMG	No corrosion	Corrosion without the impact on reliability and life time, following AEC-Q102 rev. A		
C12 H2S Class B C13 FMG			No corrosion	Corrosion without the impact on reliability and life time, following AEC-Q102 rev. A
Class for H2S Test & FMG		Description		
		H2S	FMG	
Class A		15 ppm with duration 336 h at 40 °C and 90% RH.	Duration 500 h at 25 °C and 75% RH. H2S concentration: 10ppb SO2 concentration: 200ppb NO2 concentration: 200ppb Cl2 concentration: 10ppb	
Class B		10 ppm with duration 500 h at 25 °C and 75% RH.		
Class for H2S Test & FMG		Description		
0		No corrosion found		
1		Corrosion without the impact on reliability and life time, following AEC-Q102 rev. A		